

EMB-Q77A

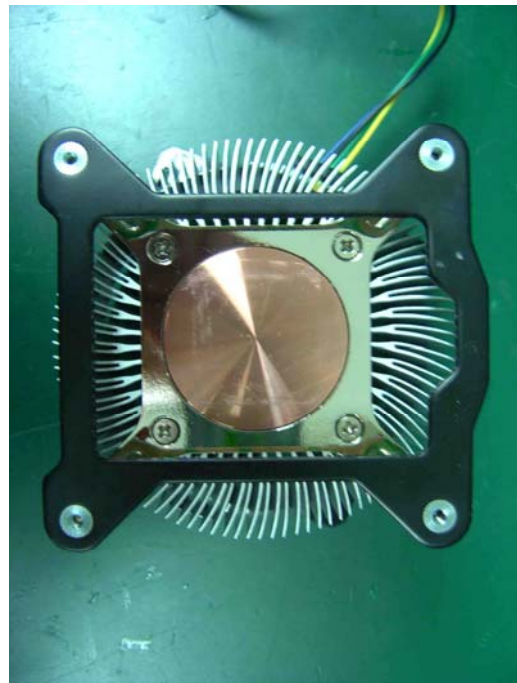
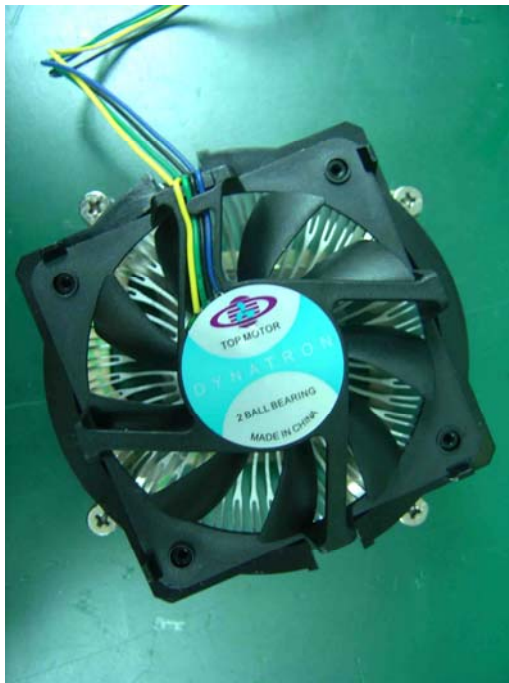
Thermal Image Analysis Report

Summary	<input type="checkbox"/> Pass <input type="checkbox"/> Fail <input checked="" type="checkbox"/> Pass with Deviation Comment: <u>Temperature points at 2 components were estimated to be in marginal temperature points in comparion with component datasheets.</u>			
	Test Result Summary			
	Critical	Major	Minor	Enhancement
Defect Found	0	0	0	2
Defect Unsolved	0	0	0	2

Issue date	Approval	Test Engineer
2013 / 03 / 28	Tom Lin	Rex Chang

Sample Configuration & Quantity Under Test

- Model name : EMB-Q77A 1.00
- CPU Board : EMB-Q77A 1.00
- CPU : Intel Core i7- 2600K / 3.4GHz
- Memory : ADATA 8GB * 2 / DDR3 1600 / Micron 2QE22 D9QBJ
- 2.5" SATA HDD : TOSHIBA MK1676GSX / 160GB
- BIOS : 0108 x64 (03/13/2013)
- Test Software : Windows 7 / Run PassMark Burn In Test 7.0 Pro
- Power : ATX Power
- CPU Cooler :



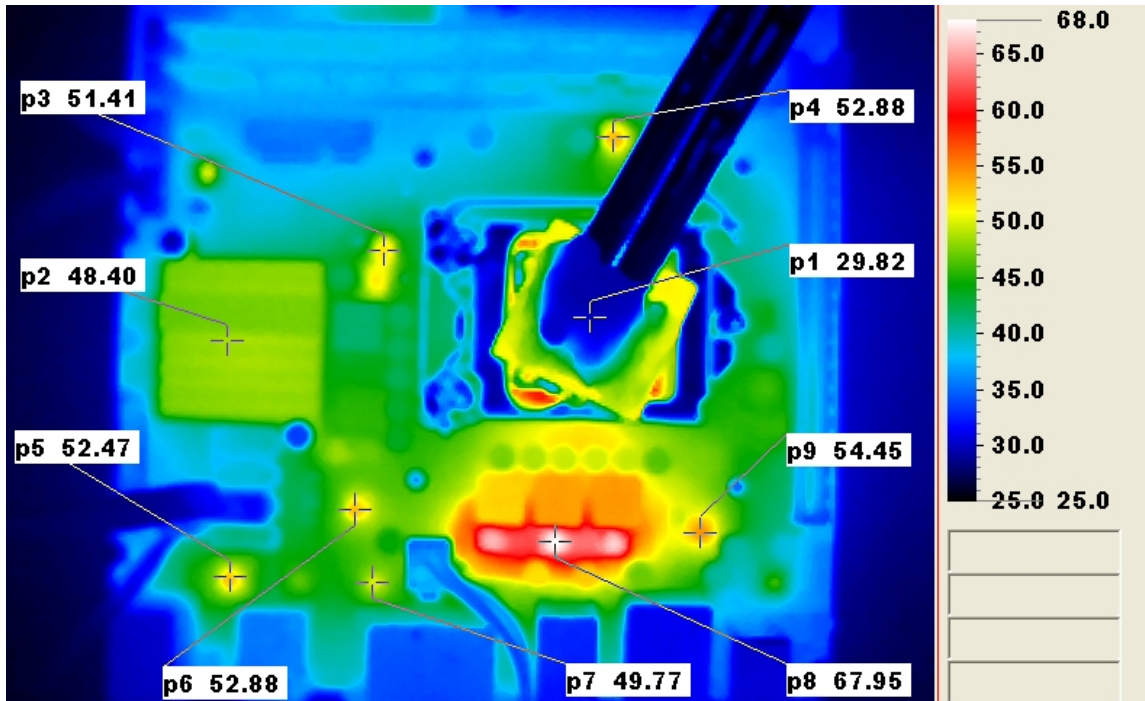
Thermal Image Analysis

1. Test Date: 2013-03-28
2. Test Product: EMB-Q77A 1.00
3. Test Site: AAEON QE Dept.
4. Temperature Measurement:
 - 4.1. 40 Channel Thermal Recorder:
 - 4.1.1 YOKOGAWA Inc,
 - 4.2.2 Model: DA100-13-1D
Date of Calibration: 2012/10/08
Serial Number: 12A323190
 - 4.2. IR Scanner: Infrared Camera
 - 4.2.1 NEC Avio Infrared Technologies Co., Ltd.
 - 4.2.2 Model: Thermo GEAR G100W2-D
Date of Calibration: 2013/01/08
Serial Number: 1051444
5. Test Condition:

Test by DA-100: 25.0°C with Heat Sink + FAN (Full speed)
6. Take Picture Time:

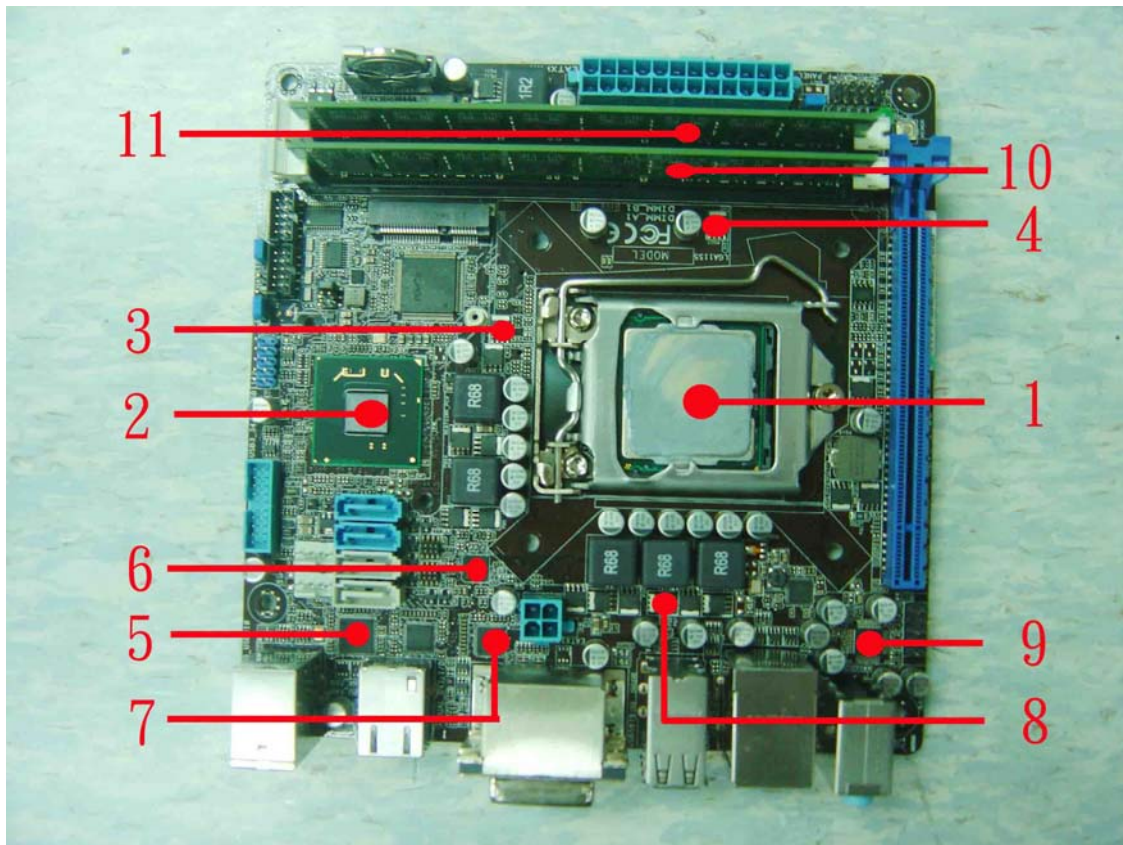
After power on 2 hours

Temperature Profile Test: Component Side:



Terminal Recorder:

Measuring Thermal Couple Position :



Using YOKOGAWA / DARWIN DA100-100-13-1D test

Point	Position	Describe	Tc (*1) (°C)	Tm (*2) Measured Under		Note
				25.0°C	60°C	
1	CPU	Intel Core I7-2600K 3.4GHz CPU	72.6	38.4	73.4	Note4
2	PCH	Intel PCH BD82Q77	85	37.0	72.0	
3	PQ20	NXP PH7030AL N-MOSFET	90	39.1	74.1	
4	PQ22	NXP PH7030AL N-MOSFET	90	40.2	75.2	
5	L2U1	Intel NIC WG82583V	85	37.8	72.8	
6	PU1	UPI UP1625SQGK	85	42.2	77.2	
7	GU1	Asmedia ASM1442	85	39.6	74.6	
8	PQ6	NXP PH2530AL	90	52.3	87.3	Note4
9	L1U1	Intel PHY WG82579	85	36.0	71.0	
10		Memory chipset - 1	95	31.1	66.1	
11		Memory chipset - 2	95	34.4	69.4	

Note(*):

- "Tc" indicates the component's case maximum temperature value specified in its datasheet.
- "Tm" indicates the measured Tc value under working environmental temperature within product specification.
- Judgment Criteria:
 - Fail : $T_m > T_c + 5^{\circ}\text{C}$; The measured value is over specification plus margin.
 - Margin : $T_c + 5^{\circ}\text{C} > T_m > T_c - 10^{\circ}\text{C}$; The measured value is within specification with margin.
 For FANLESS system application, it is strongly recommended to add thermal dissipation design for better reliability.
 - Pass : $T_m < T_c - 10^{\circ}\text{C}$; The measured value is with safety margin.
- Defect NO. [BUL1304QED01](#)